

ABSTRACT OF THE DISCLOSURE

A plurality of one-sided conductive pattern films made of resin films are piled up to form a pile with sandwiching in a given region a release film that is easily released from the resin films. The pile is then heated and pressurized to form a multi-layer board. After components are mounted on the surface of the multi-layer board, the multi-layer board and the release film are separated from each other. At least one separation board is then folded at an angle relative to a position prior to being separated. Components are mounted on the released surfaces of the separation boards. Thus, newly mounting the components on the released surfaces of the separation boards enables high-density mounting without enlarging the superficial dimensions of the multi-layer itself and adding a new board.